Dicer saw
ADT

Description
The ADT dicing saw is fully programmable microprocessor controlled saw intended to be used for cutting wafer thin materials into smaller component pieces.

Typically silicon wafers are diced but any thin material can be cut with the correct configuration and blade type.

The maximum thickness is only limited by the blades that are available.

Specifications / Capabilities

- **Substrates:** silicon, quartz, sapphire, alumina ceramics, glass, metals.
- **Samples size:** up to 8" wafers
- **Substrate thickness range:** 130μm – 2.5 mm.
- **Width of the cut:** about 100μm
- **Dicing precision (including the edge chipping):** for silicon samples – up to 30μm, for thick glasses – up to 60μm

- **Die size limitation:** at wafer thicknesses over 500μm – 1x1mm
  at wafer thicknesses less than 500μm – 3x3mm

Materials

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Link

http://www.adt-co.com/